

## ● 1.General Description

The WP5401 is a USB Type-C port protection chip that provides 20-V Short-to-VBUS overvoltage and IEC ESD protection.

By integrating low on-resistance power switch and low capacitance TVS, the WP5401 protects USB Type-C ports CC, SBU that undergoing overvoltage and IEC 61000-4-2 system level ESD without interfering with normal operation.

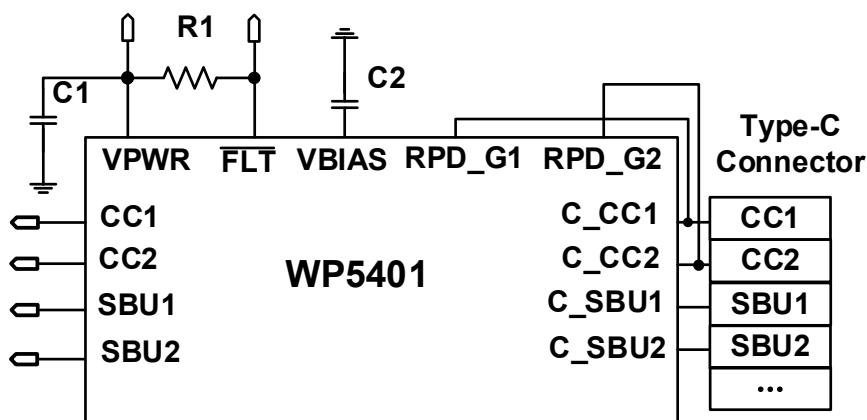
## ● 2. Features

- Short to VBUS Overvoltage Protection for CC1, CC2, SBU1 and SBU2
- IEC 61000-4-2 ESD Protection for CC1, CC2, SBU1, SBU2
- Fast OVP response for CCX and SBUX
- CC Dead Battery Resistors integrated for handling dead battery use case in mobile devices
- Package: WLCSP16

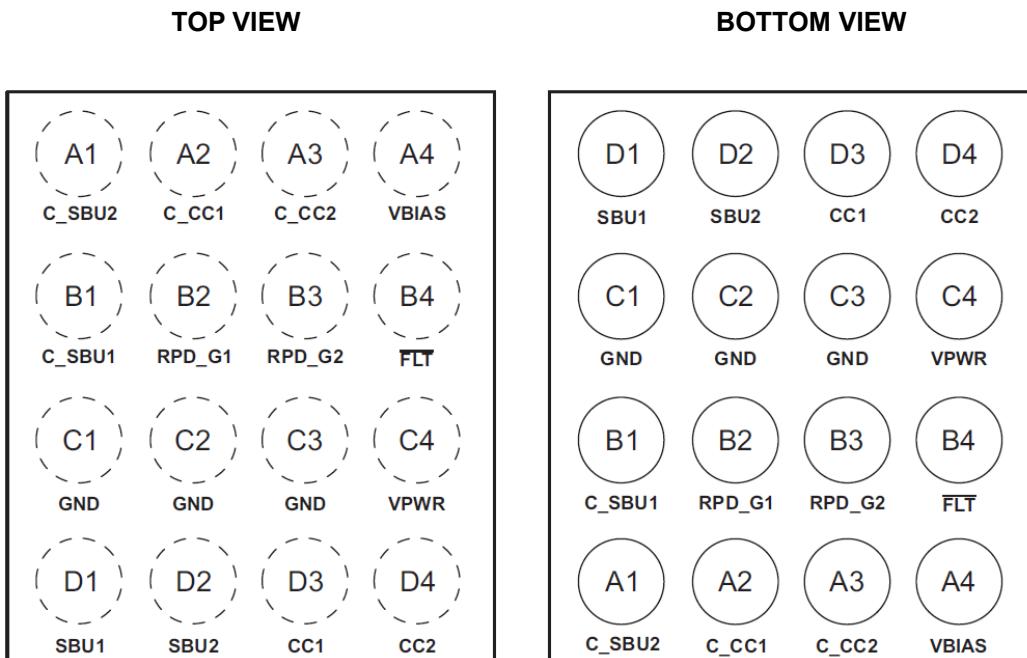
## ● 3. Applications

- Laptop PC
- Tablets
- Smart phones
- Monitors and TVS
- Docking Stations

## ● 4. Typical Application



## ● 5. Pin Configuration



## ● 6. Pin Description

PIN NUMBER	PIN NAME	I/O	PIN FUNCTIONS
A1	C_SBU2	I/O	Connector side of the SBU2 OVP FET. Connect to either SBU pin of the USB Type-C connector.
A2	C_CC1	I/O	Connector side of the CC1 OVP FET. Connect to either CC pin of the USB Type-C connector.
A3	C_CC2	I/O	Connector side of the CC2 OVP FET. Connect to either CC pin of the USB Type-C connector.
A4	VBIAS	Power	Pin for ESD support capacitor. Place a 0.1- $\mu$ F capacitor on this pin to ground.
B1	C_SBU1	I/O	Connector side of the SBU1 OVP FET. Connect to either SBU pin of the USB Type-C connector.
B2	RPD_G1	I/O	Short to C_CC1 if dead battery resistors are needed. If dead battery resistors are not needed, short pin to GND.
B3	RPD_G2	I/O	Short to C_CC2 if dead battery resistors are needed. If dead battery resistors are not needed, short pin to GND.
B4	FLT	O	Open drain for fault reporting. Under over temperature & over voltage conditions, pull low. Otherwise stay high-Z. Connect to VPWR by external resistor.
C1, C2, C3	GND	GND	Ground.

PIN NUMBER	PIN NAME	I/O	PIN FUNCTIONS
C4	VPWR	Power	2.7V - 4.5V power supply.
D1	SBU1	I/O	System side of the SBU1 OVP FET. Connect to either SBU pin of the SBU MUX.
D2	SBU2	I/O	System side of the SBU2 OVP FET. Connect to either SBU pin of the SBU MUX.
D3	CC1	I/O	System side of the CC1 OVP FET. Connect to either CC pin of the CC/PD controller.
D4	CC2	I/O	System side of the CC2 OVP FET. Connect to either CC pin of the CC/PD controller.

## ● 7. Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

PARAMETER		RATING	UNIT
Input Voltage	VPWR	-0.3 to 5	V
	RPD_G1, RPD_G2	-0.3 to 24	V
Output Voltage	FLT	-0.3 to 6	V
	VBIAS	-0.3 to 24	V
I/O Voltage	CC1, CC2, SBU1, SBU2	-0.3 to 6	V
	C_CC1, C_CC2, C_SBU1, C_SBU2	-0.3 to 24	V
Output Current	CC1, CC2	1.25	A
Operating Free Air Temperature		-40 to 85	°C
Storage Temperature		-85 to 150	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## ● 8. ESD Ratings—JEDEC Specification

PARAMETER		VALUE	UNIT
Electrostatic Discharge	Human-Body Model (HBM), Per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±4000	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Pins listed as ±2000 V may actually have higher performance.

## ● 9. ESD Ratings—IEC Specification

PARAMETER		VALUE	UNIT
Electrostatic Discharge	IEC 61000-4-2, C_SBU1, C_SBU2	Contact Discharge	±6000
		Air-gap Discharge	±15000
	IEC 61000-4-2, C_CC1, C_CC2	Contact Discharge	±3500
		Air-gap Discharge	±15000
Lightning and Surge	IEC 61000-4-5, C_CC1, C_CC2, C_SBU1, C_SBU2	±35	V

## ● 10. Recommended Operating Conditions

(Over operating free-air temperature range, unless otherwise noted)

SYMBOL	PARAMETER		MIN	TYP.	MAX	UNIT
$V_{IN}$	Input Voltage	VPWR	2.7	3.3	4.5	V
		RPD_G1, RPD_G2	0		5.5	V
$V_{OUT}$	$\overline{FLT}$ Pull-up Resistor Power Rail		2.7		5.5	V
$V_{IO}$	I/O Voltage	CC1, CC2, C_CC1, C_CC2	0		5.5	V
		SBU1, SBU2, C_SBU1, C_SBU2	0		4.3	V
$I_{VCONN}$	$V_{CONN}$ Current	Current flowing into CC1/2 and flowing out of C_CC1/2, $V_{CCX} - V_{C_{CCX}} \leq 250$ mV			600	mA
$I_{VCONN}$	$V_{CONN}$ Current	Current flowing into CC1/2 and flowing out of C_CC1/2, $T_J \leq 105^\circ\text{C}$			1.25	A
	External Components <sup>(1)</sup>	$\overline{FLT}$ Pull-up Resistance	1.7		300	kΩ
		VBIAS Capacitance <sup>(2)</sup>		0.1		μF
		VPWR Capacitance	0.3	1		μF

(1) For recommended values for capacitors and resistors, the typical values assume a component placed on the board near the pin. Minimum and maximum values listed are inclusive of manufacturing tolerances, voltage derating, board capacitance, and temperature variation. The effective value presented must be within the minimum and maximums listed in the table.

(2) The VBIAS pin requires a minimum 35-V<sub>DC</sub> rated capacitor. A 50-V<sub>DC</sub> rated capacitor is recommended to reduce capacitance derating. See the VBIAS Capacitor Selection section for more information on selecting the VBIAS capacitor.

## ● 9. Electrical Characteristics

(Over operating free-air temperature range, unless otherwise noted)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP.	MAX	UNIT
<b>CC OVP Switches</b>						
$R_{ON}$	On resistance of CC OVP FETs, $T_J \leq 85^\circ\text{C}$	$\text{CCX} = 5.5 \text{ V}$		300	600	$\text{m}\Omega$
$R_{ONFLAT}$	On resistance flatness	Sweep $\text{CCX}$ voltage between 0V and 1.2V			5	$\text{m}\Omega$
$C_{ON\_CC}$	Equivalent on capacitance	Capacitance from $\text{C}_{\text{CCX}}$ or $\text{CCX}$ to GND. $V_{C_{\text{CCX}}/\text{VCCX}} = 0 \text{ V to } 1.2 \text{ V}$ , $f = 400 \text{ kHz}$	30	74	90	$\text{pF}$
$R_{D\_DB}$	Dead battery pull-down resistance (only present when device is unpowered). Effective resistance of RD and FET in series	$V_{C_{\text{CCX}}} = 2.6 \text{ V}$	4.1	5.1	6.1	$\text{k}\Omega$
$V_{TH\_DB}$	Threshold voltage of the pulldown FET in series with RD during dead battery	$I_{CC} = 80 \mu\text{A}$	0.5	0.9	1.2	$\text{V}$
$V_{OVPCC}$	OVP threshold on CC pins	Place 5.5 V on $\text{C}_{\text{CCX}}$ . Step up $\text{C}_{\text{CCX}}$ until the $\overline{\text{FLT}}$ pin is asserted	5.75	6	6.2	$\text{V}$
$V_{OVPCC\_HYS}$	Hysteresis on CC OVP	Place 6.5 V on $\text{C}_{\text{CCX}}$ . Step down the voltage on $\text{C}_{\text{CCX}}$ until the $\overline{\text{FLT}}$ pin is deasserted. Measure difference between rising and falling OVP threshold for CC		50		$\text{mV}$
$BW_{ON}$	On bandwidth single ended (-3 dB)	Measure the -3-dB bandwidth from $\text{C}_{\text{CCX}}$ to $\text{CCX}$ . Single ended measurement, 50Ω system $V_{CM} = 0.1 \text{ V to } 1.2 \text{ V}$		100		$\text{MHz}$
$V_{STBUS\_CC}$	Short-to-VBUS tolerance on the CC pins	Hot-Plug $\text{C}_{\text{CCX}}$ with a 1meter USB Type C Cable, place a 30-Ω load on $\text{CCX}$			24	$\text{V}$

**USB Type-C Port Protector: Short-to-VBUS  
Overvoltage and IEC ESD Protection**

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP.	MAX	UNIT
$V_{STBUS\_CC\_CLAMP}$	Short-to-VBUS system-side clamping voltage on the CC pins (CCX)	Hot-Plug C_CCX with a 1-meter USB Type C Cable. Hot-Plug voltage C_CCX = 24 V. VPWR = 3.3 V. Place a 3Ω load on CCX		6		V

**SBU OVP Switches**

$R_{ON}$	On resistance of SBU OVP FETs	SBUX = 3.6 V, $-40^{\circ}C \leq T_J \leq +85^{\circ}C$		3.5	6.5	Ω
$R_{ONFLAT}$	On resistance flatness	Sweep SBUX voltage between 0 V and 3.6 V. $-40^{\circ}C \leq T_J \leq +85^{\circ}C$		1	1.5	Ω
$C_{ON\_SBU}$	Equivalent on capacitance	Capacitance from SBUX or C_SBUX to GND. Measure at $V_{C\_SBUX}/V_{SBUX} = 0.3$ V to 3.6 V		9		pF
$V_{OVPSBU}$	OVP threshold on SBU pins	Place 3.6 V on C_SBUX. Step up C_SBUX until the $\overline{FLT}$ pin is asserted	4.3	4.5	4.75	V
$V_{OVPSBU\_HYS}$	Hysteresis on SBU OVP	Place 5 V on C_CCX. Step down the voltage on C_CCX until the $\overline{FLT}$ pin is deasserted. Measure difference between rising and falling OVP threshold for C_SBUX		60		mV
$BW_{ON}$	On bandwidth single ended (-3 dB)	Measure the -3-dB bandwidth from C_SBUX to SBUX. Single ended measurement, 50-Ω system. $V_{CM} = 0.1$ V to 3.6 V		1000		MHz
$X_{TALK}$	Crosstalk	Measure crosstalk at $f = 1$ MHz from SBU1 to C_SBU2 or SBU2 to C_SBU1. $V_{CM1} = 3.6$ V, $V_{CM2}=0.3$ V. Be sure to terminate open sides to 50 Ω		-80		dB
$V_{STBUS\_SBU}$	Short-to-VBUS tolerance on the SBU pins	Hot-Plug C_SBUX with a 1-meter USB Type C Cable. Put a 40Ω resistor to GND on SBUX			24	V

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP.	MAX	UNIT
$V_{STBUS\_SBU\_CLAMP}$	Short-to-VBUS system-side clamping voltage on the SBU pins (SBUX)	Hot-Plug C_SBUX with a 1-meter USB Type C Cable. Hot-Plug voltage $V_{C\_SBUX} = 24$ V. $V_{PWR} = 3.3$ V. Put a $40\Omega$ resistor to GND on SBUX		4.5		V

**Power Supply and Leakage Currents**

$V_{PWR\_UVLO}$	VPWR under voltage lockout	Place 1 V on VPWR and raise voltage until SBU or CC FETs turn on	2.1	2.3	2.5	V
$V_{PWR\_UVLO\_HYS}$	VPWR UVLO hysteresis	Place 3 V on VPWR and lower voltage until SBU or CC FETs turnoff; measure difference between rising and falling UVLO to calculate hysteresis		100		mV
$I_{VPWR}$	VPWR supply current	$V_{PWR} = 3.3$ V (Typical), $V_{PWR} = 3.6$ V (Maximum). $-40^\circ C \leq T_J \leq +85^\circ C$ .		70	120	$\mu A$
$I_{CC\_LEAK}$	Leakage current for CC pins when device is powered	$V_{PWR} = 3.3$ V, $V_{C\_CCX} = 3.6$ V, CCX pins are floating, measure leakage into C_CCX pins. Result must be same if CCX side is biased and C_CCX is left floating.			5	$\mu A$
$I_{SBU\_LEAK}$	Leakage current for SBU pins when device is powered	$V_{PWR} = 3.3$ V, $V_{C\_SBUX} = 3.6$ V, SBUX pins are floating, measure leakage into C_SBUX pins. Result must be same if SBUX side is biased and C_SBUX is left floating. $-40^\circ C \leq T_J \leq 85^\circ C$ .			3	$\mu A$
$I_{C\_CC\_LEAK\_OVP}$	Leakage current for CC pins when device is in OVP	$V_{PWR} = 0$ V or $3.3$ V, $V_{C\_CCX} = 24$ V, CCX pins are set to 0 V, Measure leakage into C_CCX pins			200	$\mu A$

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SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP.	MAX	UNIT
I <sub>C_SBU_LEAK_OVP</sub>	Leakage current for SBU pins when device is in OVP	V <sub>PWR</sub> = 0 V or 3.3 V, V <sub>C_SBUX</sub> = 24 V, SBUX pins are set to 0 V, measure leakage into C_SBUX pins			200	µA
I <sub>CC_LEAK_OVP</sub>	Leakage current for CC pins when device is in OVP	V <sub>PWR</sub> = 0 V or 3.3 V, V <sub>C_CCX</sub> = 24 V, CCX pins are set to 0 V, measure leakage out of CCX pins			30	µA
I <sub>SBU_LEAK_OVP</sub>	Leakage current for SBU pins when device is in OVP	V <sub>PWR</sub> = 0 V or 3.3 V, V <sub>C_SBUX</sub> = 24 V, SBUX pins are set to 0 V, measure leakage out of SBUX pins	-1		1	µA
I <sub>DX_LEAK</sub>	Leakage current for Dx pins	V <sub>DX</sub> = 3.6 V, measure leakage into Dx pins			1	µA

**FLT Pin**

V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 3 mA. Measure the voltage at the FLT pin			0.4	V
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**Over Temperature Protection**

T <sub>SD_RISING</sub>	The rising over-temperature protection shutdown threshold		170		°C
T <sub>SD_FALLING</sub>	The falling over-temperature protection shutdown threshold		135		°C
T <sub>SD_HYST</sub>	The over-temperature protection shutdown threshold hysteresis		35		°C

**Power-On and Off Timings**

t <sub>ON</sub>	Time from crossing rising VPWR UVLO until CC and SBU OVP FETs are on			3.5	ms
d <sub>VPWR_OFF/dt</sub>	Minimum slew rate allowed to guarantee CC and SBU FETs turnoff during a power off	-0.5			V/µs

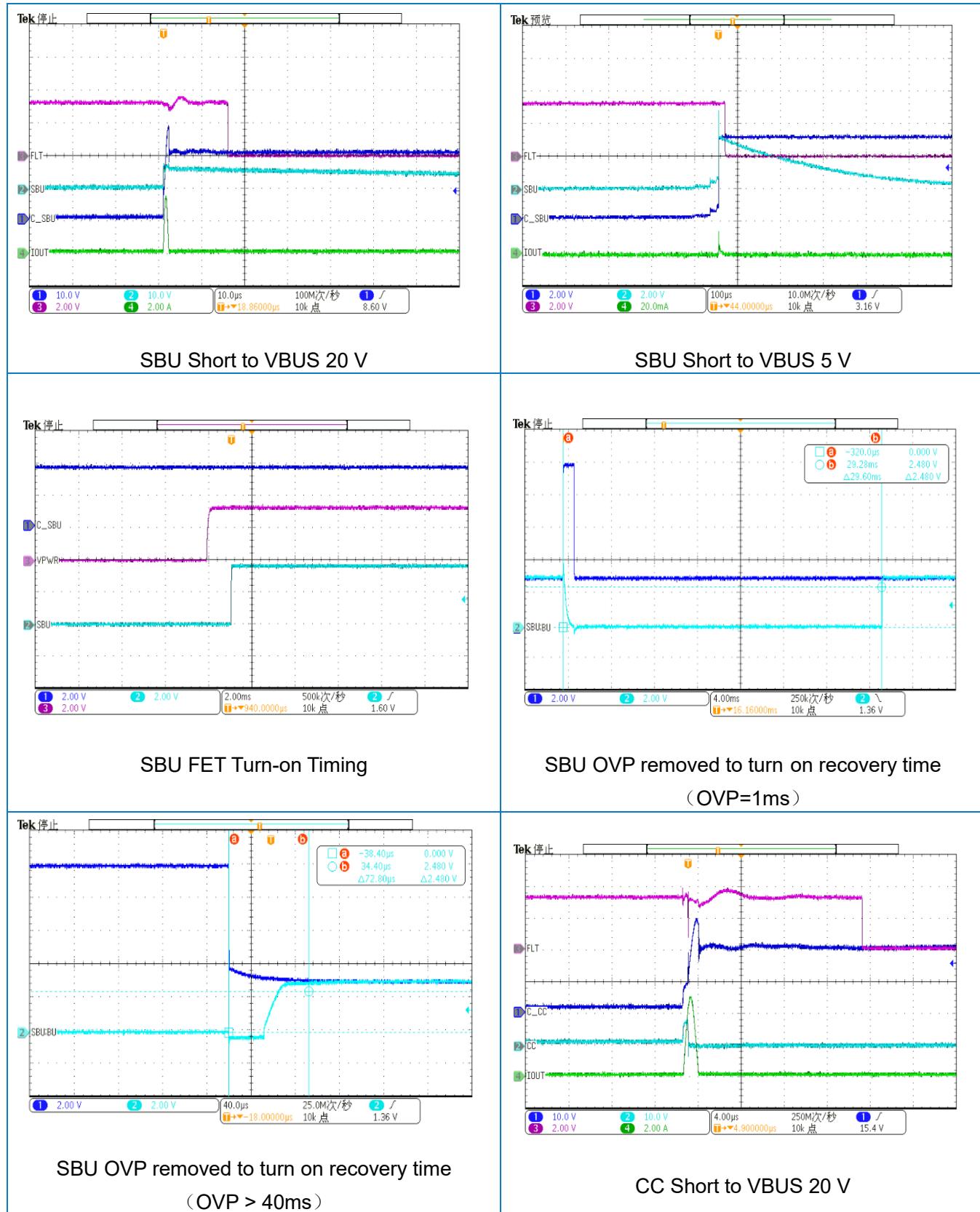
**Over Voltage Protection**

t <sub>OVP_RESPON_SE_CC</sub>	OVP response time on the CC pins. Time from OVP asserted until OVP FETs turnoff		80		ns
t <sub>OVP_RESPON_SE_SBU</sub>	OVP response time on the SBU pins. Time from OVP asserted until OVP FETs turnoff		130		ns

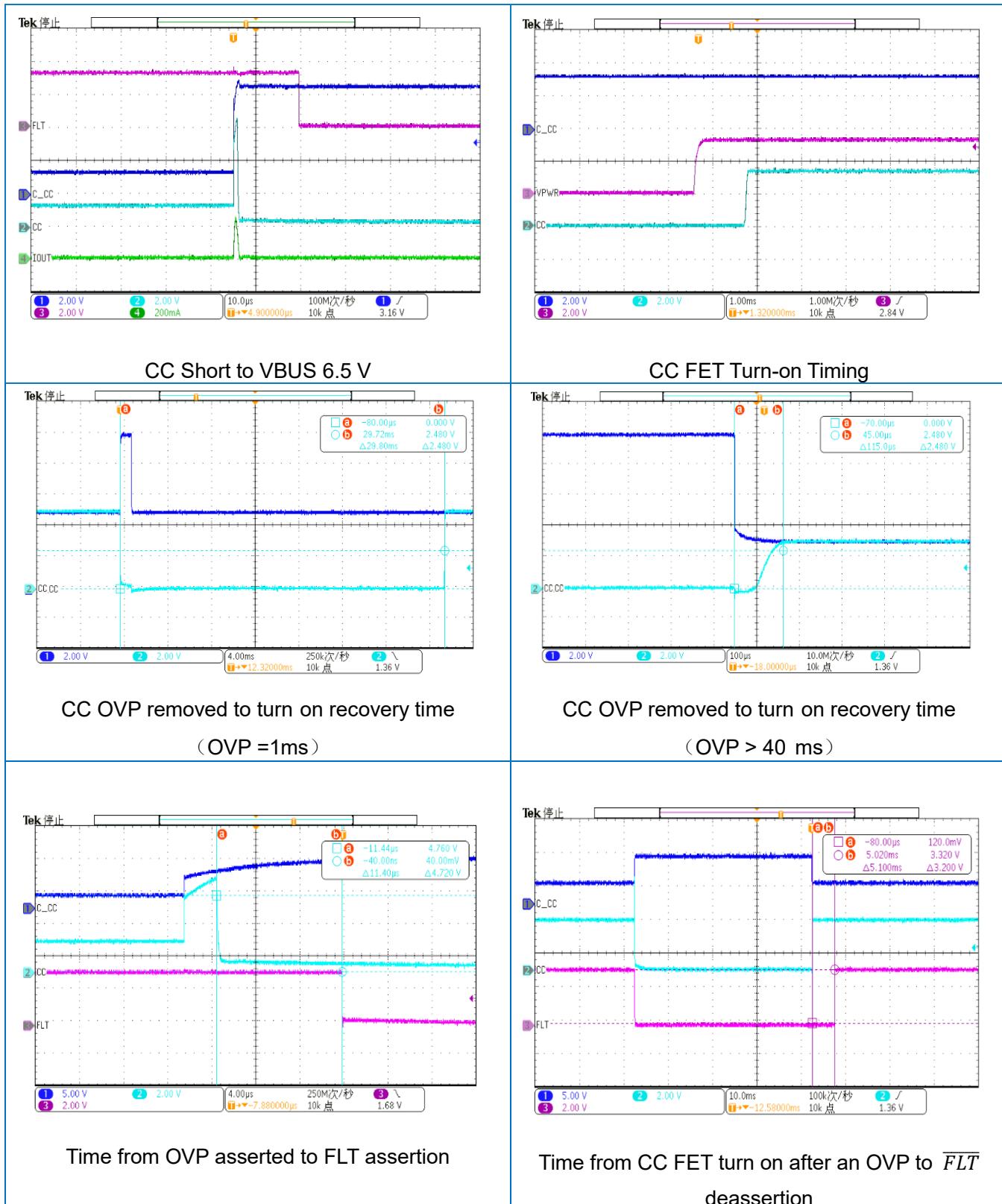
SYMBOL	PARAMETER	MIN	TYP.	MAX	UNIT
t <sub>OVP_RECOVE</sub> RY_CC_1	OVP recovery time on the CC pins. Once an OVP has occurred, the minimum time duration until the CC FETs turn back on. OVP must be removed for CC FETs to turn back on	21	33	39	ms
t <sub>OVP_RECOVE</sub> RY_SBU_1	OVP recovery time on the SBU pins. Once an OVP has occurred, the minimum time duration until the SBU FETs turn back on. OVP must be removed for SBU FETs to turn back on	21	32	39	ms
t <sub>OVP_RECOVE</sub> RY_CC_2	OVP recovery time on the CC pins. Time from OVP removal until CC FET turns back on, if device has been in OVP > 40 ms		0.1		ms
t <sub>OVP_RECOVE</sub> RY_SBU_2	OVP recovery time on the SBU pins. Time from OVP removal until SBU FET turns back on, if device has been in OVP > 40 ms		0.1		ms
t <sub>OVP_FLT_ASS</sub> ETION	Time from OVP asserted to $\overline{\text{FLT}}$ assertion		12		$\mu\text{s}$
t <sub>OVP_FLT_DEA</sub> SSERTION	Time from CC FET turn on after an OVP to $\overline{\text{FLT}}$ Deassertion		5		ms

## ● 10. Typical Performance Characteristics

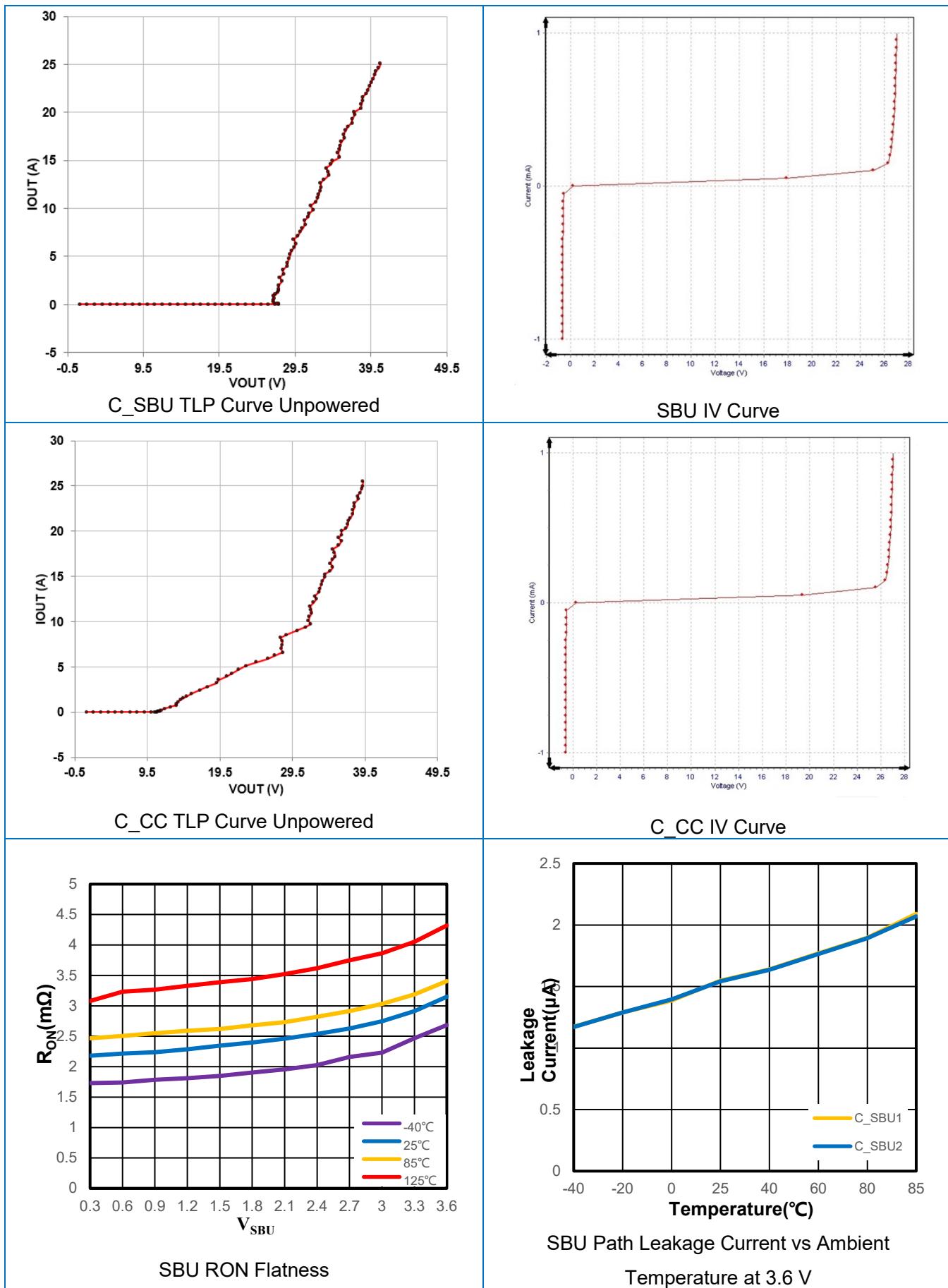
( $V_{PWR} = 3.3V$ ,  $T_A = 25^\circ C$ ,  $C_1 = 1\mu F$ ,  $C_2 = 0.1\mu F$ ,  $R_1 = 100k\Omega$ , unless otherwise noted)



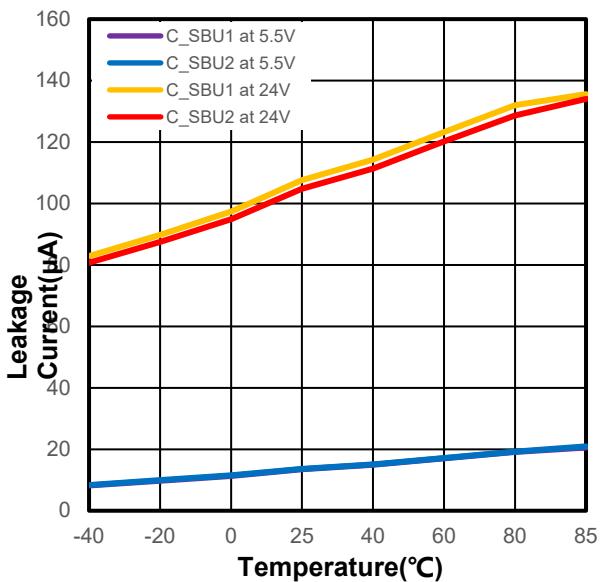
## USB Type-C Port Protector: Short-to-VBUS Overvoltage and IEC ESD Protection



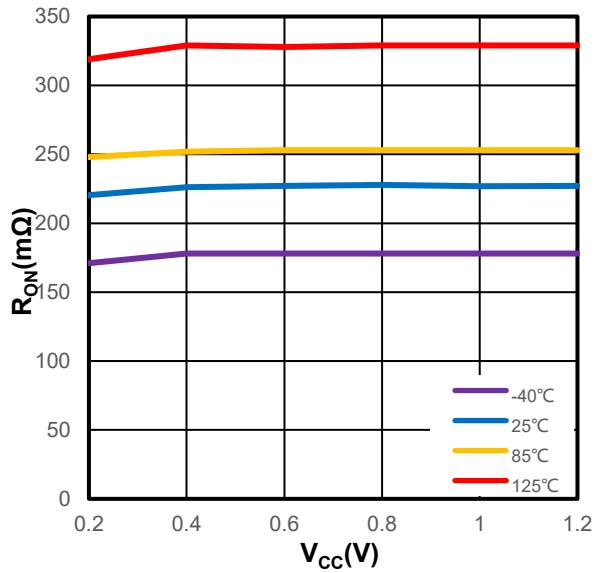
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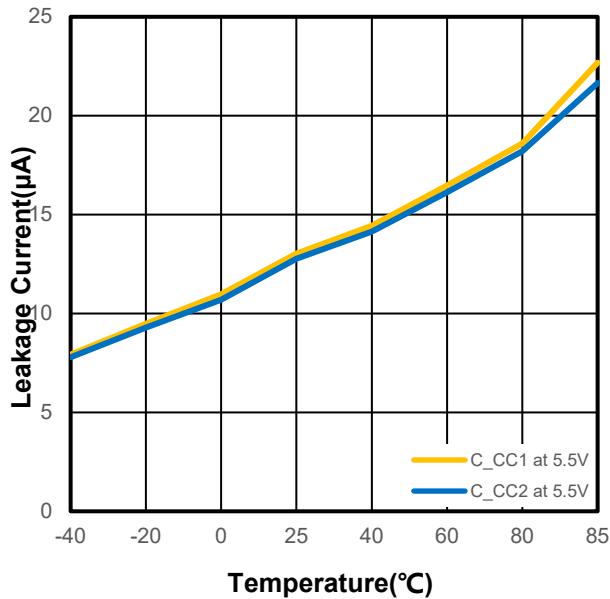
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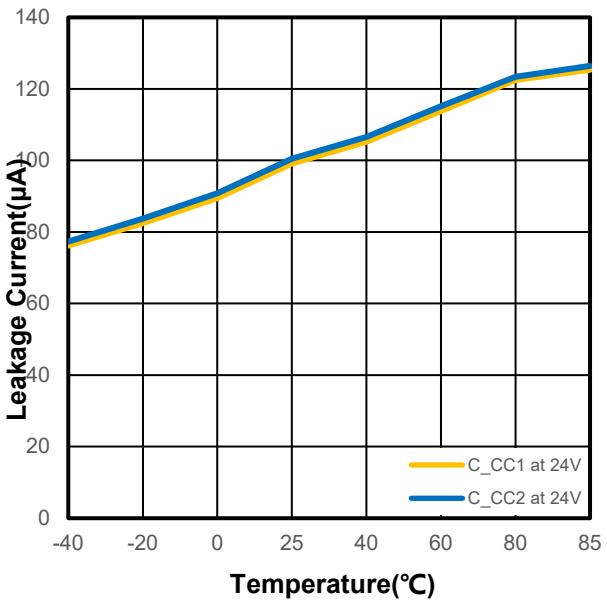
C\_SBU OVP Leakage Current vs Ambient Temperature at 5.5 V and 24 V



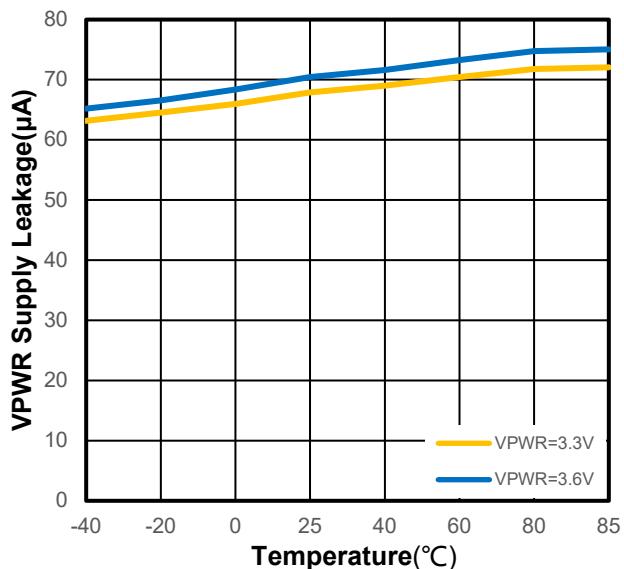
CC RON Flatness



C\_CC Path Leakage Current vs Ambient Temperature at C\_CC = 5.5 V



C\_CC Path Leakage Current vs Ambient Temperature at C\_CC = 24 V



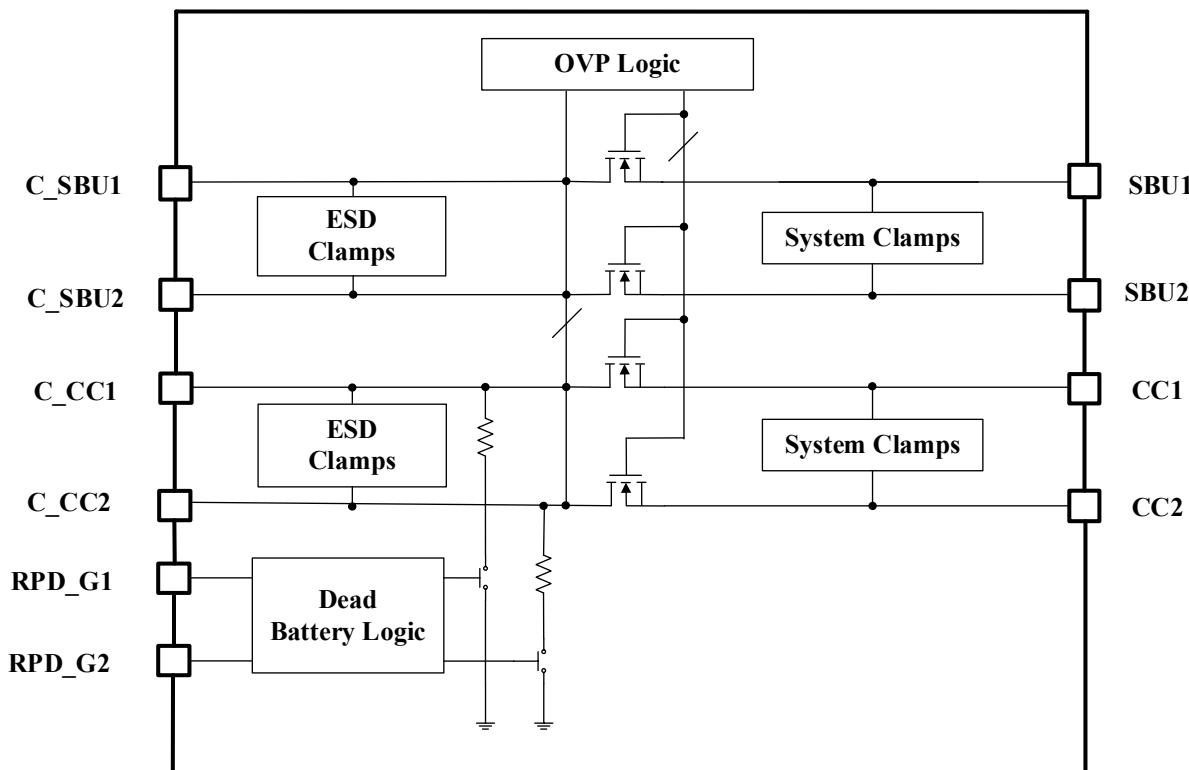
VPWR Supply Leakage vs Ambient Temperature  
at 3.3V and 3.6V

- **11. Function Description**

- **11.1 Overview**

The WP5401 is a USB Type-C port protection chip that integrates four channels of 20-V Short-to-VBUS overvoltage protection for the CC1, CC2, SBU1, and SBU2 pins and six channels of IEC61000-4-2 ESD protection for the CC1, CC2, SBU1, SBU2, pins of the USB Type-C connector.

## 11.2 Block Diagram



- **11.3 Feature Description**

- **11.3.1 4-Channels of Short-to-VBUS Overvoltage Protection (CC1, CC2, SBU1, SBU2 Pins): 24-V<sub>DC</sub> Tolerant**

The WP5401 provides 4-channels of Short-to-VBUS Overvoltage Protection for the CC1, CC2, SBU1, and SBU2 pins of the USB Type-C connector. The WP5401 is able to handle 24-VDC on its C\_CC1, C\_CC2, C\_SBU1, and C\_SBU2 pins. This is necessary because according to the USB PD specification, with VBUS set for 20-V operation, the VBUS voltage is allowed to legally swing up to 21 V, and 21.5 V on voltage transitions from a different USB PD VBUS voltage.

- **11.3.2 4-Channels of IEC 61000-4-2 ESD Protection (CC1, CC2, SBU1, SBU2 Pins)**

The WP5401 integrates 4-Channels of IEC 61000-4-2 system level ESD protection for the CC1, CC2, SBU1, SBU2 pins.

USB Type-C ports on end-products need system level IEC ESD protection in order to provide adequate protection for the ESD events that the connector can be exposed to from end users.

- **11.3.3 Thermal Shutdown**

Thermal shutdown protects the part from internally or externally generated excessive temperatures. During an overtemperature condition the switch is turned off. The switch automatically turns on again if the temperature of the die drops below the threshold temperature.

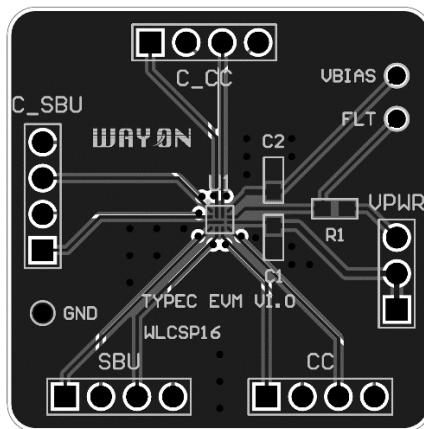
- **11.3.4 Dead-battery Mode**

The WP5401 integrates high voltage dead battery RD pull-down resistors to allow dead battery charging simultaneously with high-voltage OVP protection. If dead battery support is required, short the RPD\_G1 pin to the C\_CC1 pin, and short the RPD\_G2 pin to the C\_CC2 pin. This connects the dead battery resistors to the connector CC pins.

- **12. Layout**

For best performance, place the bypass capacitors as close as possible to the VPWR pin, and ESD protection capacitor as close as possible to the VBIAS pin. The USB2.0 and SBU lines must be routed as straight as possible and any sharp bends must be minimized.

- **12.1 Layout Example**



- **13 Evaluation Modules**

Evaluation Modules (EVMs) are available to help evaluate initial circuit performance. We have evaluation modules for different packages, you can contact us by phone or address at the end to get the evaluation module or schematic.

The module names are listed in the table below.

NAME	PACKAGE	EVALUATION MODULE
WP5401	WLCSP16	TYPEC EVM V1.0 WLCSP16

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- **14 Naming Conventions**

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**WP AB CC-DDD E**

**WP:** WAYON Protection IC;

**A:** Product Category –5: Type C Protection;

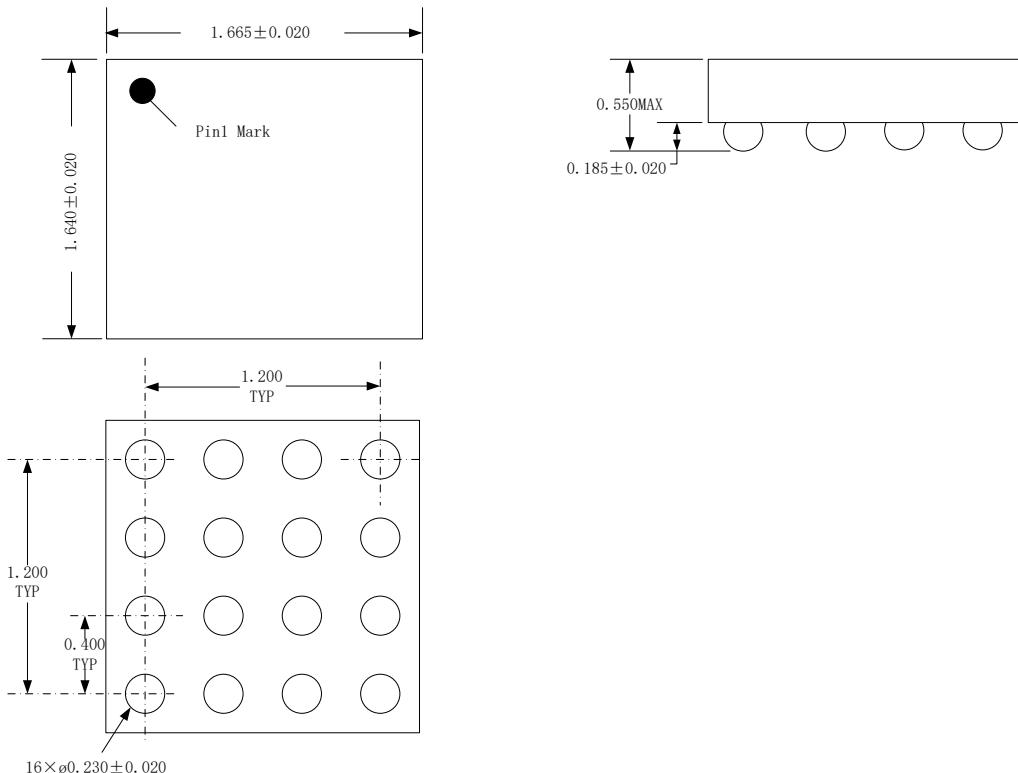
**B:** Number of Protection Channels – 4: 4 Channels;

**CC:** Serial Number;

**DDD:** Package – C16: WLCSP 16;

**E:** R-Reel & T-tube;

## ● 15 Package Information

**WLCSP 16**

## ● 16 Ordering Information

PART NUMBER	PACKAGE	PACKING QUANTITY	MARKING*
WP5401-C16R	WLCSP 16	3k/Reel	WP5401 XXXX

## Contact Information

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For additional information, please contact your local Sales Representative.

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*Specifications are subject to change without notice.*

*The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.*

*Users should verify actual device performance in their specific applications.*

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